



MRSI Solutions

For Dispense and Assembly

Volume XVI

Welcome to MRSI Solutions Newsletter. This periodic newsletter provides information on our latest happenings and product updates.

Many thanks to our loyal customers for their continued interest in our products.

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Die Bonding with Integrated In Situ UV Curing

In situ UV Epoxy Dispensing, Die Bonding & Curing

One challenge in building photonic devices such as Active Optical Cables (AOC) is to ensure extremely accurate post die bond positioning of lenses or other critical devices. In situ UV epoxy curing results in more accurate post bond placement by eliminating movement during thermal curing. Parts are held in place during UV curing, which drives higher accuracies and thus higher product yield.

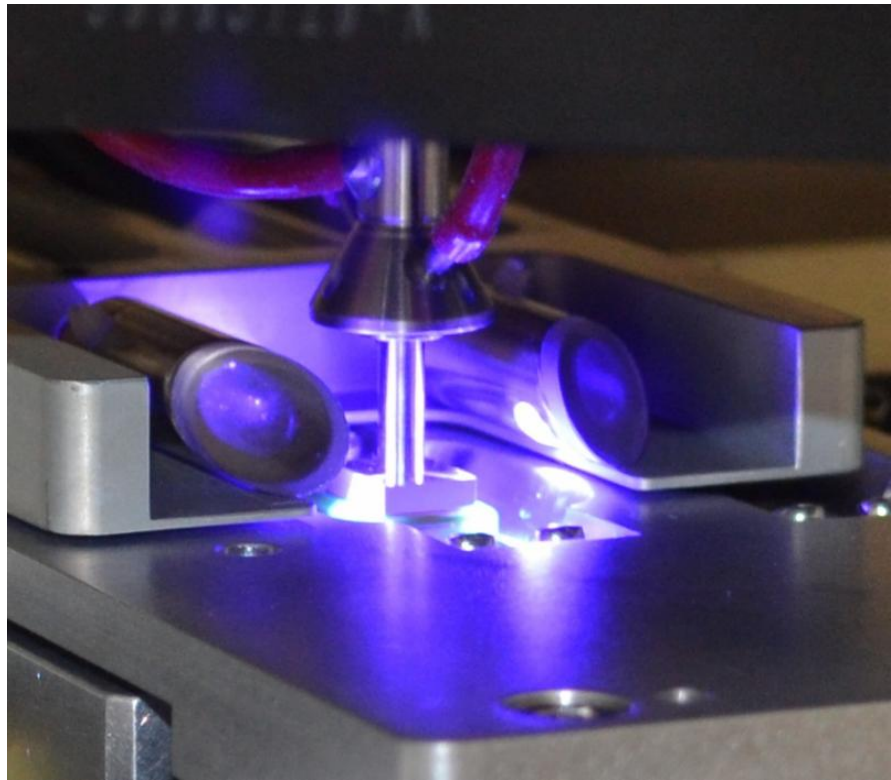
MRSI ultra-precision die bonders are available with fully integrated UV curing. Features include specialized UV epoxy processes and dispense hardware, including easy-clean, accurate time/pressure dispense pumps for short pot-life materials. In addition, dispense needle auto-shutter light guards ensure that the dispense needle tips do not clog due to inadvertent UV exposure. Safety considerations include light tight enclosure with electrical interlocks and UV safety glass windows. Flexible fixturing design and adjustable UV light paths provide the flexibility needed for a wide range of package geometries and types. The UV light source can be LED or lamp. The UV lamp provides a broad spectrum of light delivered through a light guide. LED sources are more flexible and reduce fixturing costs. Interchangeable LED heads provide the required wavelength of light for specific UV epoxy materials.

Features and benefits include:

- Specialized dispense hardware for ease-of-use
- Dispense needle guards for a robust, high uptime process
- Safety considerations for operator safety
- Flexible fixturing design to accommodate multiple part types
- Adjustable light paths allow many part geometries
- LED UV light option simplifies required fixturing
- UV lamp cure for broad spectrum UV curing

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In Situ_UV Curing

International Microelectronics Assembly and Packaging Society News

Jon Mederach of MRSI is President Elect for the New England IMAPS Chapter.

The International Microelectronics Assembly and Packaging Society (IMAPS) is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging technologies through professional education.

The New England Chapter is very active with six technical and social events throughout the year, as well as the annual Symposium and Expo each May. New England is the largest chapter in the entire IMAP society.

For the last two years Jon has served as General Chair of the Symposium, which brought together more than 50 vendors and presented 35 technical papers in addition to a poster session for university students.

As President, Jon and other dedicated volunteers are committed to continue to promote the Society's goals. The New England Chapter of IMAPS has always stressed the importance of technical advancement and knowledge, along with having an enjoyable time. This combination is a key factor making the chapter unique and successful in the recruitment of quality leaders and new members, while making the meetings informative and stimulating.

Jon recently celebrated his fifteenth year at MRSI Systems in his position of Sales Manager for the Eastern Region. Jon attends numerous trade shows and conferences throughout the year and is busy traveling to visit his many customers.



President Elect



IMAPS New England Conference and Exhibits

Upcoming Events: IMS and ECTC

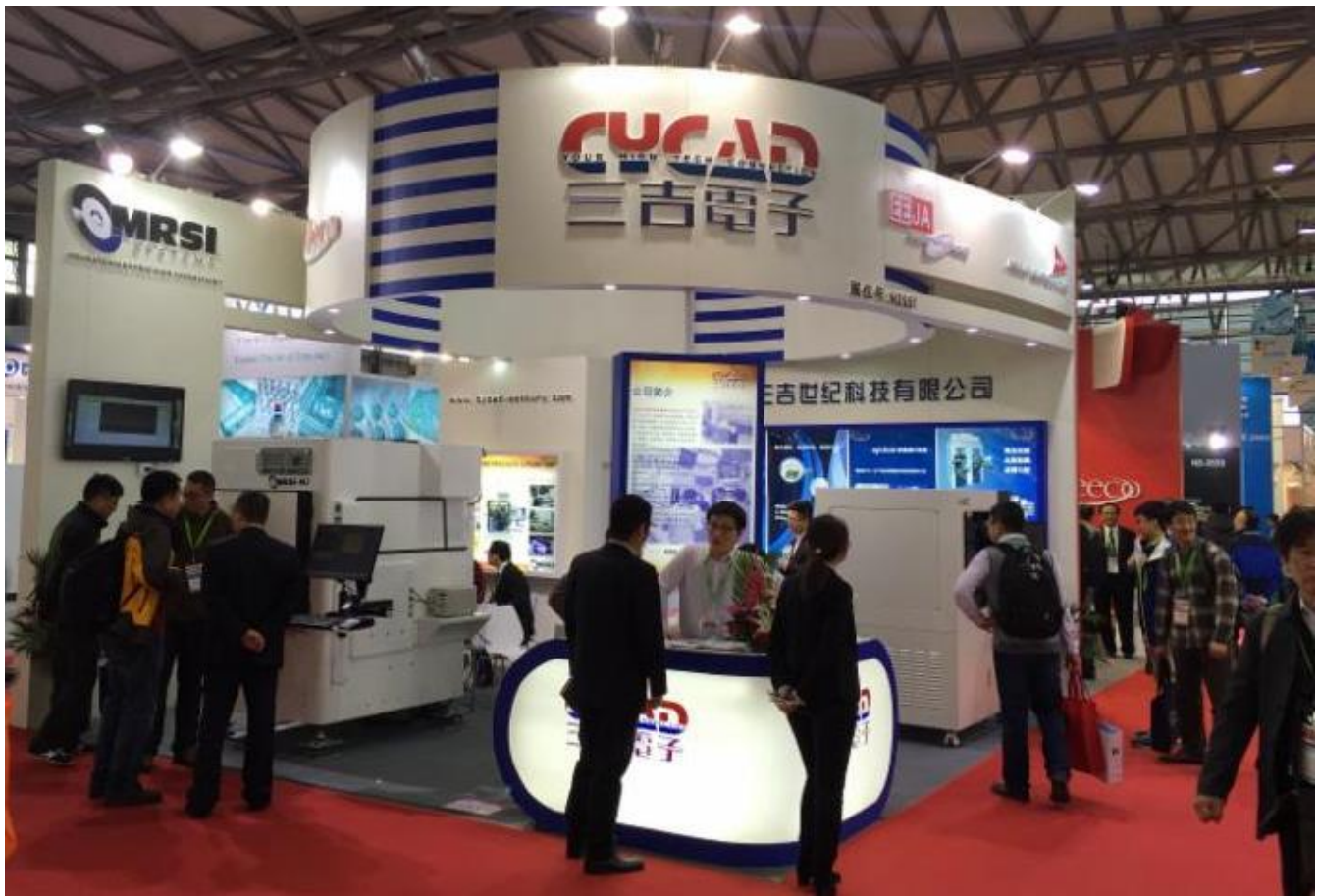
Thanks to our loyal customers and partners for making the recent events such a major success. MRSI recently exhibited at Semicon China, OFC, IMAPS 12th International Conference and Exhibition on Device Packaging and was a gold sponsor at the IMAPS New England conference and exhibits.

2016 show schedule continues with two big events in May including;

- International Microwave Symposium (IMS), May 22nd - 27th 2016
Booth #342, San Francisco, CA
- IEEE 66th Electronic Components and Technology Conference (ECTC)
May 31st - June 3rd 2016 Booth #122, Las Vegas, NV

We hope to see you there!

You are always welcome to come visit us at our Billerica, MA factory. Contact us with your dispensing and assembly challenges. Chances are we have already solved similar ones.



Semicon China

MRSI - M Series
1-3 Micron Assembly Work Cell



MRSI - 705
5 Micron Assembly Work Cell



MRSI-175Ag
Epoxy Dispenser



http://r20.rs6.net/tn.jsp?f=001MFzMQYNvIOto0UaCx3h5SQTYXGy-CsXivEaQalyEheG7fsH9nFaW6d0UE6p_3M8zbZ1X1rPzPg36OU37AKHY2hq7LEWFplhOa-jFjqldkQq71DhAl-ZyTCeVVDJog8OMPpl4etCjvkeh9lfwnmRncqTTYHbZ9SxGC-whv0lgmQ=&c=jt_lo4sHxjPhu0bubUAJKA9mJ9S4LPVyO6sgqgFVXGy7m4yYn069rQ==&ch=X-5SEPBTeerFvafgjqAsMaFhIWaS0D1kLe51rcZUe7w-GtvWab98fA==

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